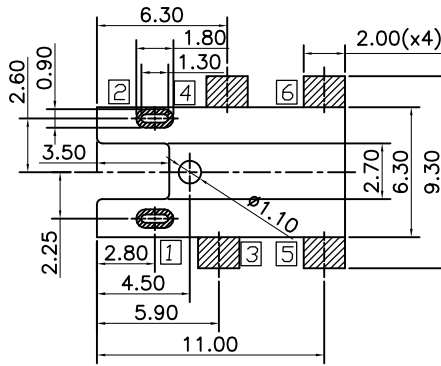
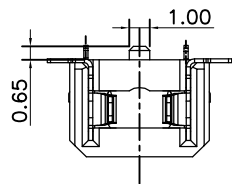
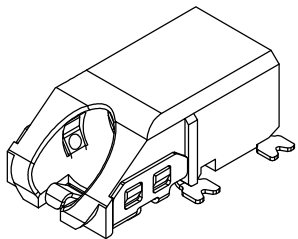
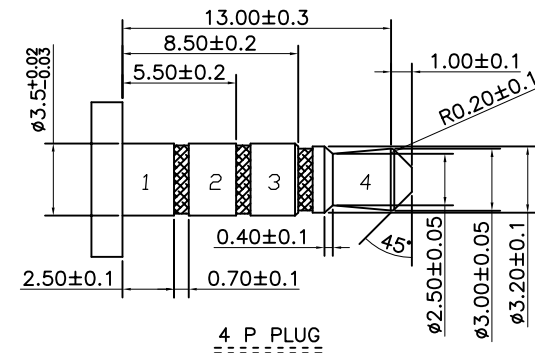


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

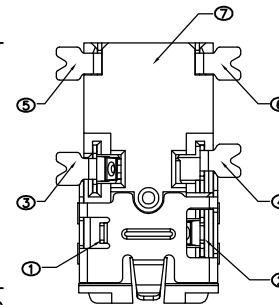
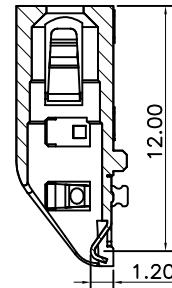
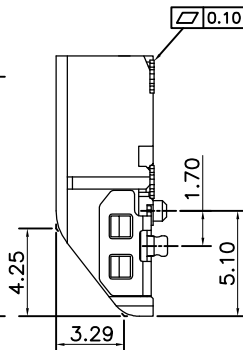
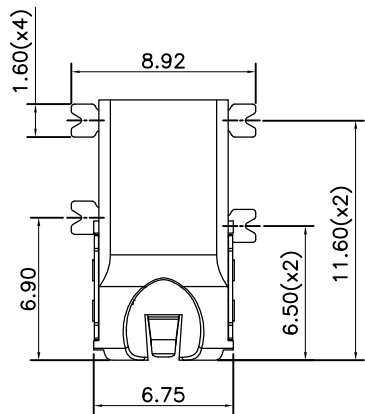
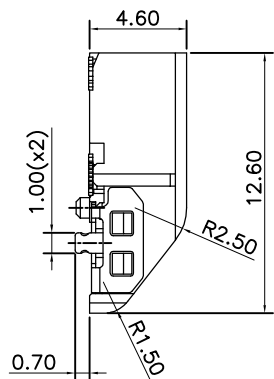
RoHS



PCB LAYOT(TOP VIEW) ±0.05



4 P PLUG



NATING:

1.0 RATING:

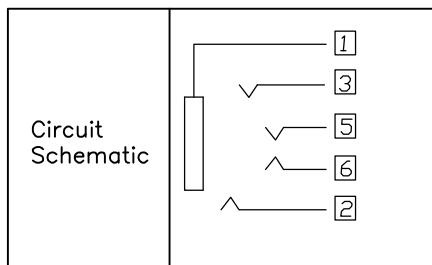
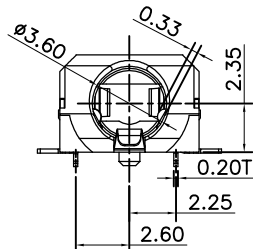
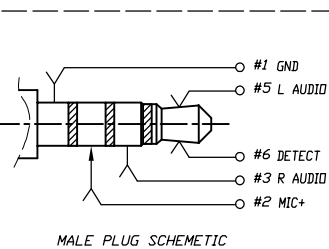
- 1.1 VOTAGE:12 VAC
- 1.2 CURRENT: I 1AMPERE MAXIMUM PER CONTACT 30° cT-RISE
- 1.3 TEMPERATURE:-25° cT0+85° c

2.0 CONTACT RESISTANCE:

- 2.1 CONTACT RESISTANCE:INITIAL 50mΩ MAX.
- 2.2 INSULATION RESISTANCE:100M MIN
- 2.3 DIELECTIC WITHSTANDING VOLTAGE:500 VAC AT SEA LEVEL

WLPJF9-06 3 X X X 0 009

PLATING: 1-G/F  
2-AU 3U"  
5-AU 15U"  
6-AU 30U"  
COLOUR: A:Black



□ TERMINAL NO  
○ ITEM NO

ITEM	NAME	MATERIAL	QTY	REMARK
7	HOUSING	PPA	1PCS	
6	TERMINAL5	C5210R-EH	1PCS	
5	TERMINAL4	C5210R-EH	1PCS	
4	TERMINAL3	C5210R-EH	1PCS	
3	TERMINAL3	C5210R-EH	1PCS	
2	TERMINAL2	C5210R-EH	1PCS	
1	TERMINAL1	C5210R-EH	1PCS	

REV.	REVISION RECORD		DATE	UNIT: mm	GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	REV: A0	SHEET: 1/1
	REVISION	DESCRIPTION			LINEAR	ANGLES							
A0	NEW RELEASE		21.01.13		0.00±0.25	X°±3°	APPROVED	Wang_jr	21.01.13	WLPJF9-063XX0009	ENDE05		
					0.00±0.10	X°X'±2°	DESIGNER	Ding_bo	21.01.13	TITLE:	PHONE JACK Ø3.5 SMT+DIP TYPE CONN		
							DRAWN	Du_jian	21.01.13				

